Science and Technology of Chemical Mechanical Planarization (CMP)

Symposium held April 14–16, 2009, San Francisco, California, U.S.A.

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PREFACE

Symposium E, “Science and Technology of Chemical Mechanical Planarization (CMP),” was held April 14–16 at the 2009 MRS Spring Meeting in San Francisco, California. This volume consists of invited, contributed, and poster presentations from national and international researchers representing universities, federal laboratories and industries. The objective of this symposium is to bring together experts from a broad spectrum of research and technology groups who are currently working on CMP challenges. This symposium addresses all aspects of integration challenges and key structural reliability issues for CMP of Cu-interconnects, MEMS, and compound semiconductors.

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February 2010
MATERIALS RESEARCH SOCIETY SYMPOSIUM PROCEEDINGS


